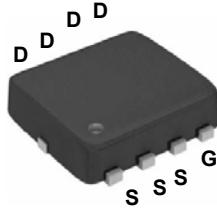
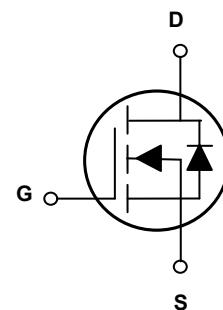


Main Product Characteristics

| | |
|---------------|-------|
| $V_{(BR)DSS}$ | 20V |
| $R_{DS(ON)}$ | 5.4mΩ |
| I_D | 65A |



PPAK3X3



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFN2306 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Max. | Unit |
|--|-----------------|-------------|------|
| Drain-Source Voltage | V_{DS} | 20 | V |
| Gate-Source Voltage | V_{GS} | ± 10 | V |
| Drain Current-Continuous ($T_C=25^\circ\text{C}$) | I_D | 65 | A |
| Drain Current-Continuous ($T_C=100^\circ\text{C}$) | | 41 | |
| Drain Current-Pulsed ¹ | I_{DM} | 260 | A |
| Power Dissipation ($T_C=25^\circ\text{C}$) | P_D | 44.6 | W |
| Power Dissipation-Derate above 25°C | | 0.36 | W/°C |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 62 | °C/W |
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 2.8 | °C/W |
| Operating Junction Temperature Range | T_J | -55 To +150 | °C |
| Storage Temperature Range | T_{STG} | -55 To +150 | °C |

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|---|--|---|------|------|-----------|----------------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$ | 20 | - | - | V |
| BV _{DSS} Temperature Coefficient | $\Delta \text{BV}_{\text{DSS}}/\Delta T_J$ | Reference to 25°C , $I_{\text{D}}=1\text{mA}$ | - | 0.01 | - | $\text{V}/^\circ\text{C}$ |
| Drain-Source Leakage Current | I_{DSS} | $V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$ | - | - | 1 | μA |
| | | $V_{\text{DS}}=16\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$ | - | - | 10 | |
| Gate-Source Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{V}$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| Static Drain-Source On-Resistance | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$ | - | 4.5 | 5.4 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=15\text{A}$ | - | 5.5 | 6.8 | |
| | | $V_{\text{GS}}=1.8\text{V}, I_{\text{D}}=10\text{A}$ | - | 6.8 | 8.8 | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$ | 0.3 | 0.6 | 1 | V |
| $V_{\text{GS}(\text{th})}$ Temperature Coefficient | $\Delta V_{\text{GS}(\text{th})}$ | | - | 2 | - | $\text{mV}/^\circ\text{C}$ |
| Forward Transconductance | g_{fs} | $V_{\text{DS}}=10\text{V}, I_{\text{s}}=5\text{A}$ | - | 20 | - | S |
| Dynamic and Switching Characteristics | | | | | | |
| Total Gate Charge ^{2, 3} | Q_g | $V_{\text{DS}}=10\text{V}, V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=6\text{A}$ | - | 29.8 | 45 | nC |
| Gate-Source Charge ^{2, 3} | Q_{gs} | | - | 2.7 | 6 | |
| Gate-Drain Charge ^{2, 3} | Q_{gd} | | - | 9 | 14 | |
| Turn-On Delay Time ^{2, 3} | $T_{\text{d}(\text{on})}$ | $V_{\text{DD}}=10\text{V}, V_{\text{GS}}=4.5\text{V}, R_G=25\Omega, I_{\text{D}}=1\text{A}$ | - | 13.5 | 26 | nS |
| Rise Time ^{2, 3} | T_r | | - | 29 | 55 | |
| Turn-Off Delay Time ^{2, 3} | $T_{\text{d}(\text{off})}$ | | - | 66.9 | 127 | |
| Fall Time ^{2, 3} | T_f | | - | 19.2 | 36 | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$ | - | 1920 | 2790 | pF |
| Output Capacitance | C_{oss} | | - | 280 | 410 | |
| Reverse Transfer Capacitance | C_{rss} | | - | 180 | 270 | |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Continuous Source Current | I_s | $V_G=V_D=0\text{V}$, Force Current | - | - | 65 | A |
| Pulsed Source Current | I_{SM} | | - | - | 130 | A |
| Diode Forward Voltage | V_{SD} | $V_{\text{GS}}=0\text{V}, I_{\text{s}}=1\text{A}, T_J=25^\circ\text{C}$ | - | - | 1 | V |

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. Pulsed tested: pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

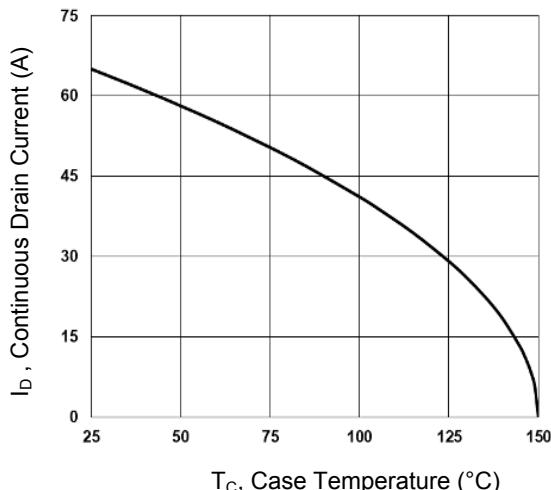


Figure 1. Continuous Drain Current vs. T_c

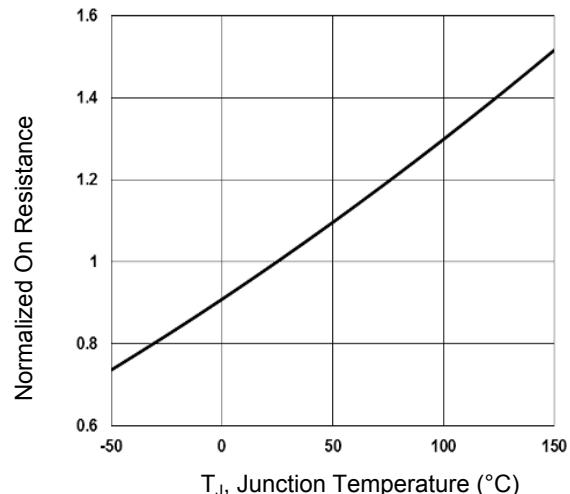


Figure 2. Normalized R_{DS(ON)} vs. T_j

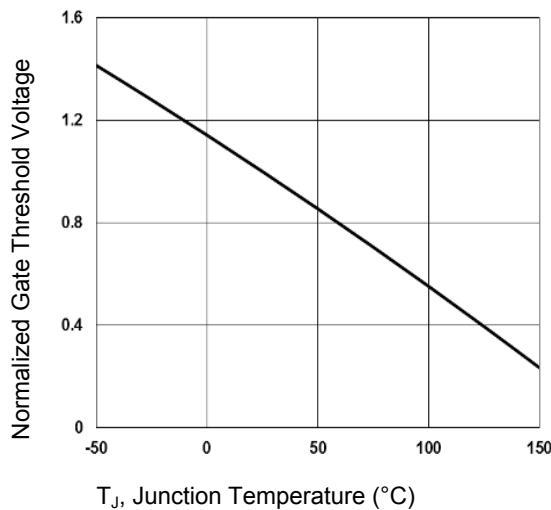


Figure 3. Normalized V_{th} vs. T_j

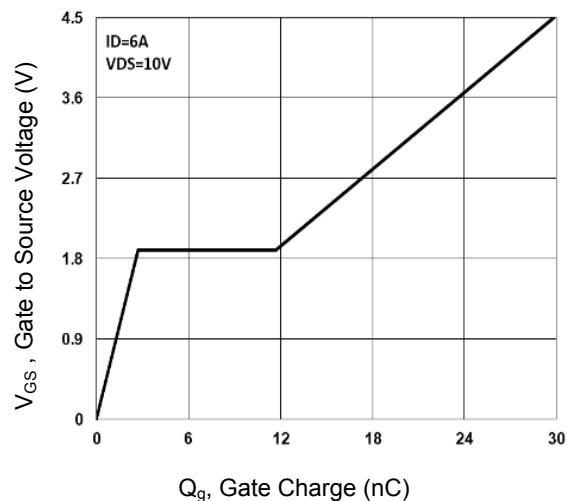


Figure 4. Gate Charge Waveform

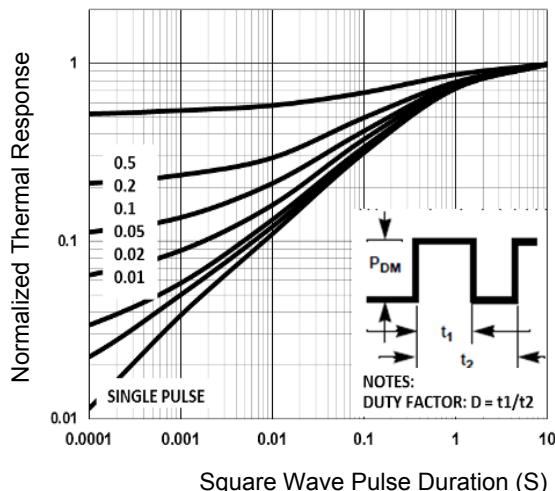


Figure 5. Normalized Transient Response

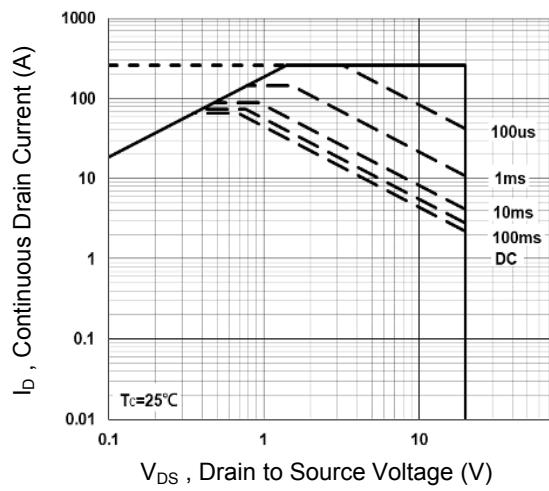


Figure 6. Maximum Safe Operation Area

Typical Electrical and Thermal Characteristic Curves

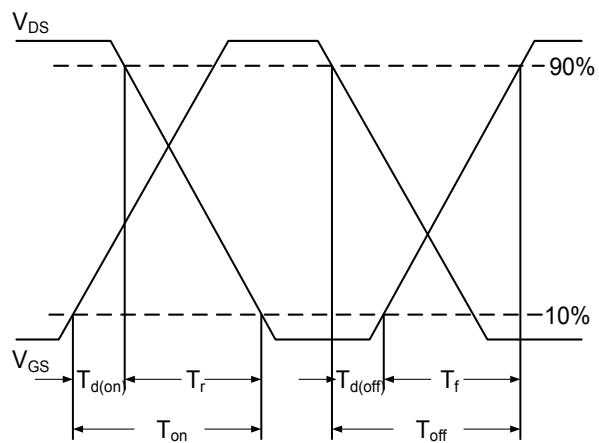


Figure 7. Switching Time Waveform

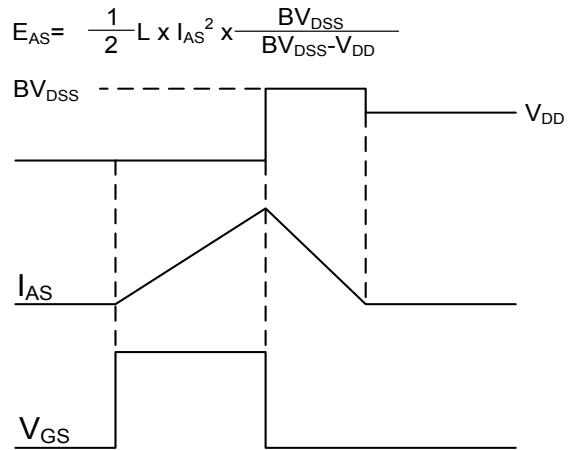
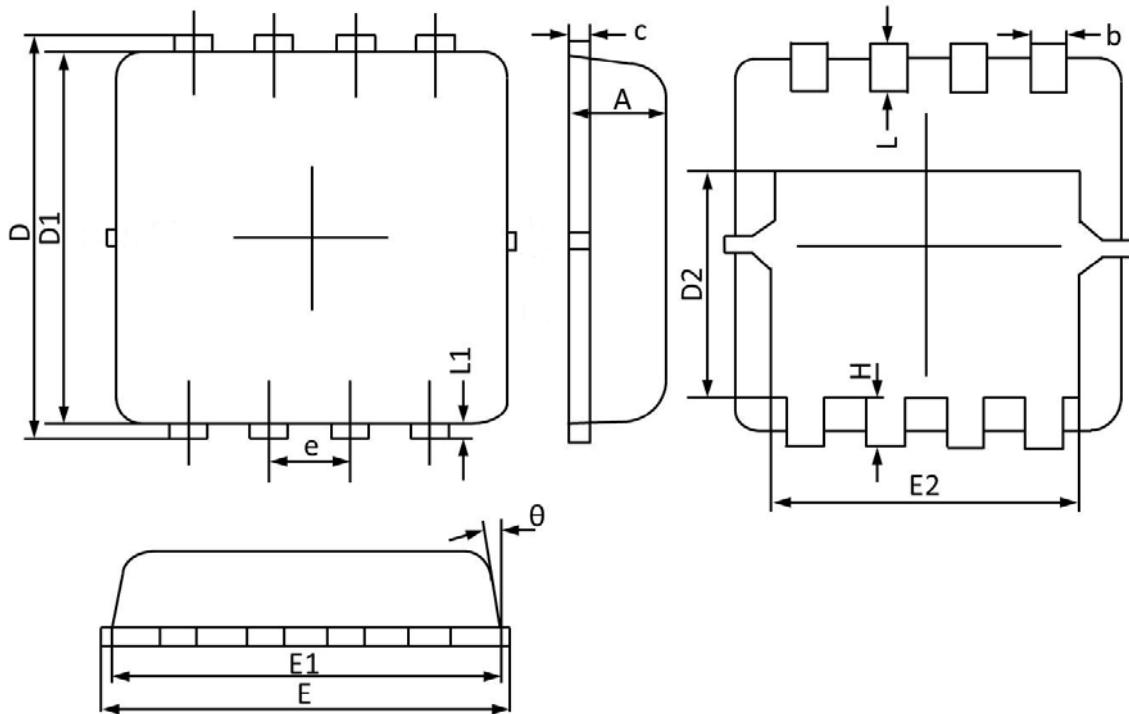


Figure 8. E_{AS} Waveform

Package Outline Dimensions

PPAK3X3



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | MAX | MIN | MAX | MIN |
| A | 0.900 | 0.700 | 0.035 | 0.028 |
| b | 0.350 | 0.240 | 0.014 | 0.009 |
| c | 0.250 | 0.100 | 0.010 | 0.004 |
| D | 3.450 | 3.050 | 0.136 | 0.120 |
| D1 | 3.200 | 2.900 | 0.126 | 0.114 |
| D2 | 1.850 | 1.350 | 0.073 | 0.053 |
| E | 3.400 | 3.000 | 0.134 | 0.118 |
| E1 | 3.250 | 2.900 | 0.128 | 0.114 |
| E2 | 2.600 | 2.350 | 0.102 | 0.093 |
| e | 0.65BSC | | 0.026BSC | |
| H | 0.500 | 0.300 | 0.020 | 0.012 |
| L | 0.500 | 0.300 | 0.020 | 0.012 |
| L1 | 0.200 | 0.070 | 0.008 | 0.003 |
| θ | 12° | 0° | 12° | 0° |